

# TIC™ 1000A

High Performance, Value Compound for High-End Computer Processors

## Features and Benefits

- High thermal performance: 0.32°C/W (@ 50 psi)
- Good screenability
- Room temperature storage
- No post "cure" required
- Exceptional value



TIC 1000A is a high performance, thermally conductive compound intended for use as a thermal interface material between a high-end computer processor and a heat sink. Other high watt density applications will also benefit from the extremely low thermal impedance of TIC 1000A.

TIC 1000A compound wets-out the thermal interface surfaces and flows to produce the lowest thermal impedance. The compound requires pressure of the assembly to cause flow. The TIC 1000A compound will resist dripping.

For microprocessor applications, traditional screw fastening or spring clamping methods will provide adequate force to optimize the thermal performance of TIC 1000A.

An optimized application would utilize the minimum volume of TIC 1000A material necessary to ensure complete wet-out of both mechanical interfaces.

### Assembly – No Post Screen Cure

TIC 1000A has good screenability. No solvent is used to reduce the viscosity, so no post "cure" conditioning is required.

TYPICAL PROPERTIES OF TIC 1000A						
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Gray	Gray	Visual			
Density (g/cc)	2.1	2.1	ASTM D792			
Continuous Use Temp (°F) / (°C)	302	150	—			
ELECTRICAL						
Electrical Resistivity (Ohm-meter) (1)	N/A	N/A	ASTM D257			
THERMAL						
Thermal Conductivity (W/m-K)	1.5	1.5	ASTM D5470			
THERMAL PERFORMANCE vs PRESSURE						
	Pressure (psi)	10	25	50	100	200
	TO-220 Thermal Performance (°C/W) (2)	0.32	0.32	0.32	0.31	0.28
1) The compound contains an electrically conductive filler surrounded by electrically non-conductive resin.						
2) TO-220 performance data is provided as a reference to compare material thermal performance.						

### Application Cleanliness

1. Pre-clean heat sink and component interface with isopropyl alcohol prior to assembly or repair. Ensure heat sink is dry before applying TIC 1000A.

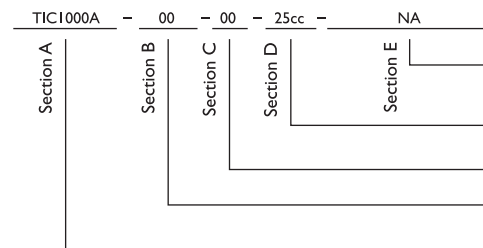
### Application Methods

1. Dispense and/or screenprint TIC 1000A compound onto the processor or heat sink surface like thermal grease (see a Bergquist Representative for application information).
2. Assemble the processor and heat sink with spring clips or constant-pressure fasteners.

## Typical Applications Include:

- High performance CPUs
- High performance GPUs

## Building a Part Number



## Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Containers: 5cc = 5.0cc, 25cc = 25.0cc, 200cc = 200.0cc  
Cartridge: 600cc = 600.0cc

00 = No options

00 = No options

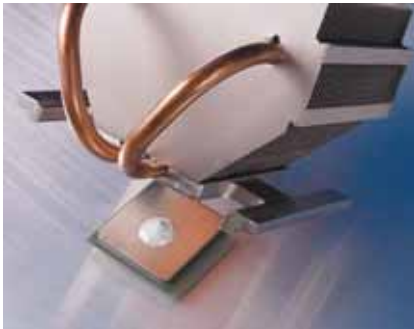
TIC1000A = Thermal Interface Compound 1000A

Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).

## High Performance Thermal Interface Compound for Copper-Based Heat Sinks

### Features and Benefits

- Thermal conductivity: 4.0 W/m-K
- Exceptional thermal performance: 0.19°C/W @ 50 psi



TIC 4000 is a thermally conductive grease compound designed for use as a thermal interface material between a computer processor and a copper-based heat sink. Other high watt density applications will benefit from the extremely low thermal impedance of TIC 4000.

TIC 4000 compound wets-out the thermal interface surfaces and flows to produce low thermal impedance. The compound requires pressure of the assembly to cause flow. TIC 4000 compound will not drip.

For a typical 0.5" x 0.5" application at 0.005" thick, Bergquist estimates approximately 0.02 ml (cc) of TIC 4000.

Although Bergquist estimates a 0.02 ml (cc) volumetric requirement for a 0.5" x 0.5" component interface, dispensed at a thickness of 0.005", Bergquist also recognizes that an optimized application would utilize the minimum volume of TIC 4000 material necessary to ensure complete wet-out of both mechanical interfaces.

TYPICAL PROPERTIES OF TIC 4000						
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Gray	Gray	Visual			
Density (g/cc)	4.0	4.0	ASTM D792			
Continuous Use Temp (°F) / (°C)	302	150	—			
<b>ELECTRICAL</b>						
Electrical Resistivity (Ohm-meter) (1)	N/A	N/A	ASTM D257			
<b>THERMAL</b>						
Thermal Conductivity (W/m-K)	4.0	4.0	ASTM D5470			
<b>THERMAL PERFORMANCE vs PRESSURE</b>						
	Pressure (psi)	10	25	50	100	200
	TO-220 Thermal Performance (°C/MW) (2)	0.21	0.20	0.19	0.19	0.18
1) The compound contains an electrically conductive filler surrounded by electrically non-conductive resin.						
2) TO-220 performance data is provided as a reference to compare material thermal performance.						

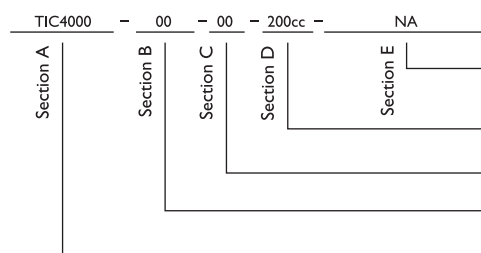
### Application Methods

1. Pre-clean heat sink and component interface with isopropyl alcohol prior to assembly or repair. Ensure heat sink is dry before applying TIC 4000.
2. Dispense TIC 4000 compound onto the processor or heat sink surface like thermal grease.
3. Assemble the processor and heat sink with clip or constant-pressure fasteners.

### Typical Applications Include:

- High performance computer processors (traditional screw fastening or clamping methods will provide adequate force to optimize the thermal performance of TIC 4000)
- High watt density applications where the lowest thermal resistance interface is required

### Building a Part Number



### Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Containers: 5cc = 5.0cc, 25cc = 25.0cc, 200cc = 200.0cc.

00 = No options

00 = No options

TIC4000 = Thermal Interface Compound 4000

Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).